

13 12 11 10 9 8 7 6 5 4 3 2 1

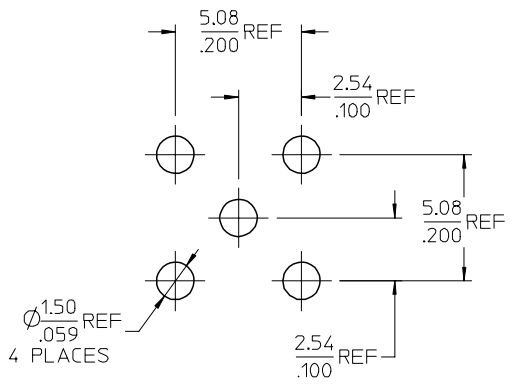
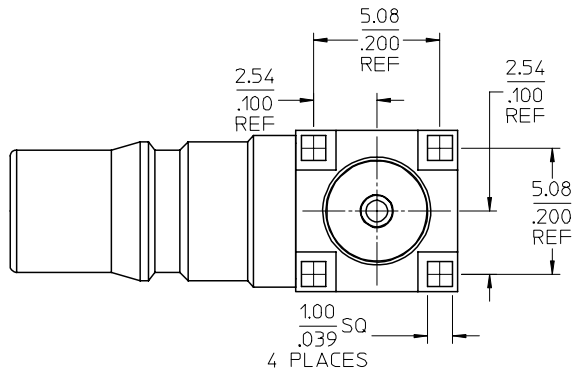
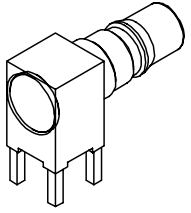
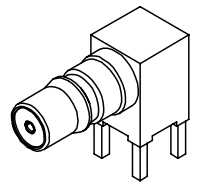
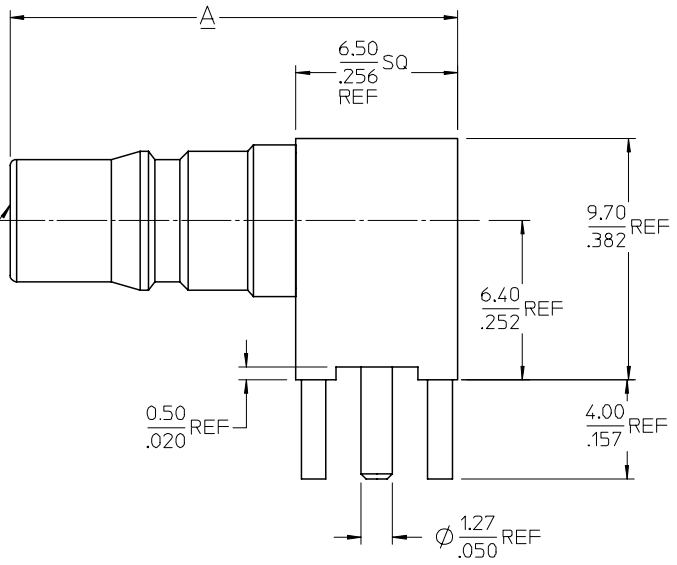
MATERIALS AND FINISHES

BODY, CAP BRASS
 PLATED GOLD (10 MICROINCHES MIN)
 OVER CHEMICAL NICKEL

INSULATOR TEFLON

CENTER CONTACT BERYLLIUM COPPER
 PLATED GOLD (10 MICROINCHES MIN)
 OVER CHEMICAL NICKEL

QMA JACK
 INTERFACE



RECOMMENDED PCB LAYOUT

73254-0242	21.00/.827 REF	BULK
73254-0241	18.00/.709 REF	P/N 73254-0240, ONE PER BAG
73254-0240	18.00/.709 REF	BULK
PART NO.	DIM A	PACKAGING

CHG: UPDATED VIEWS WITH REVISED BODY AND INSULATOR.
 EC NO: URF2008-0002
 DRWN: ARROBERTSON 2007/07/03
 CHKD: 2007/07/03
 APPR: JIM ENEER 2007/07/03
 A3

QUALITY SYMBOLS
 ▽=0
 ▽=0
 DESCRIPTION

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± .005	± .0005
3 PLACES ± .003	± .0003
2 PLACES ± .002	± .0002
1 PLACE ± .001	± .0001
ANGULAR ± 2 °	

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	
MM/IN	
DRAWN BY	DATE
SSS	2005/02/08
CHECKED BY	DATE
TEF	2005/02/08
APPROVED BY	DATE
JDW	2005/02/08
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
METRIC		
		☉
QMA JACK, R/A, PCB 50 OHMS, EWR2710 QMA-J/PCB		
molex MOLEX INCORPORATED		
MATERIAL NO.	DOCUMENT NO.	SHEET NO.
	SD-73254-024	1 OF 1
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

12 11 10 9 8 7 6 5 4 3 2 1